SUBMINIATURE SOLID STATE LAMP

Part Number: KM2520SGC09 Super Bright Green

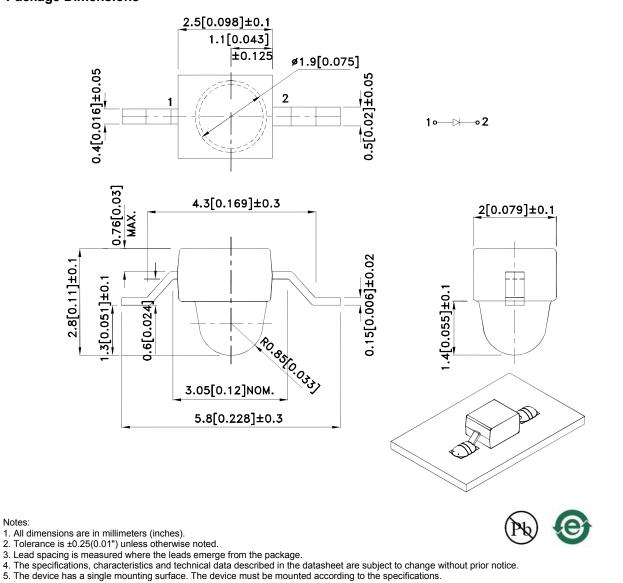
Features

- Subminiature package.
- Z-bend lead.
- Long life solid state reliability.
- Low package profile.
- Moisture sensitivity level : level 3.
- Package : 1000pcs / reel.
- RoHS compliant.

Package Dimensions

Description

The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.



SPEC NO: DSAA5216 APPROVED: WYNEC REV NO: V.14B CHECKED: Allen Liu DATE: MAR/30/2013 DRAWN: Y.Liu PAGE: 1 OF 5 ERP: 1202000634

Selection Guide

Part No.	Dice	Lens Type	lv (mo @ 20	/ - -	Viewing Angle [1]
			Min.	Тур.	201/2
KM2520SGC09	Super Bright Green (GaP)	Water Clear	40	90	20°

Notes:

1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Green	565		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Super Bright Green	568		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Green	30		nm	I⊧=20mA
С	Capacitance	Super Bright Green	15		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	Super Bright Green	2.2	2.5	V	I⊧=20mA
lr	Reverse Current	Super Bright Green		10	uA	VR=5V

Notes:

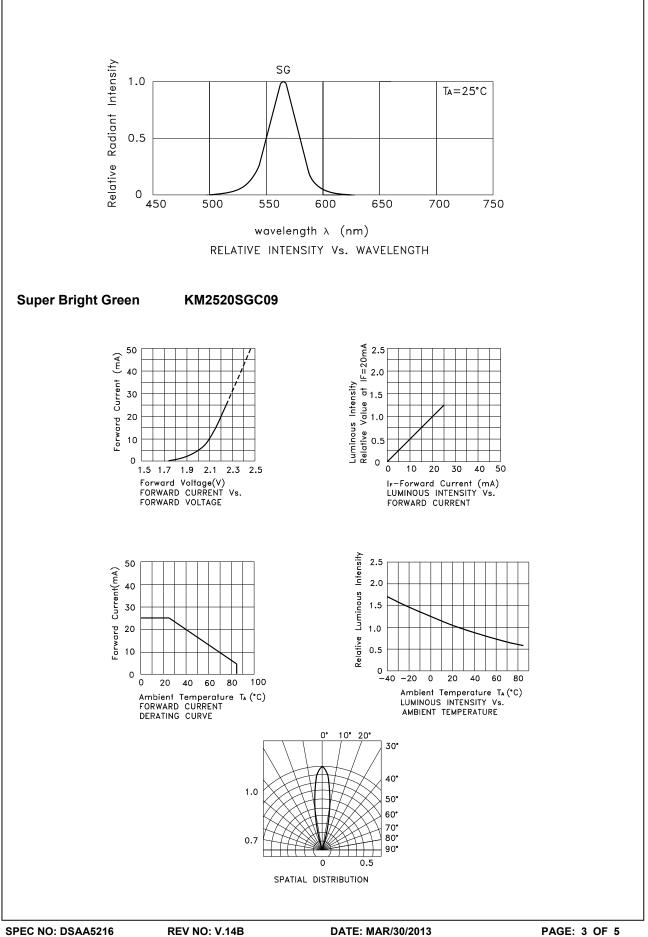
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Green	Units	
Power dissipation	62.5	mW	
DC Forward Current	25	mA	
Peak Forward Current [1]	140	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

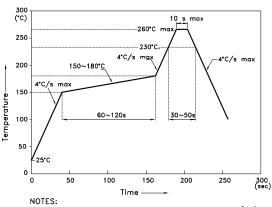
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.



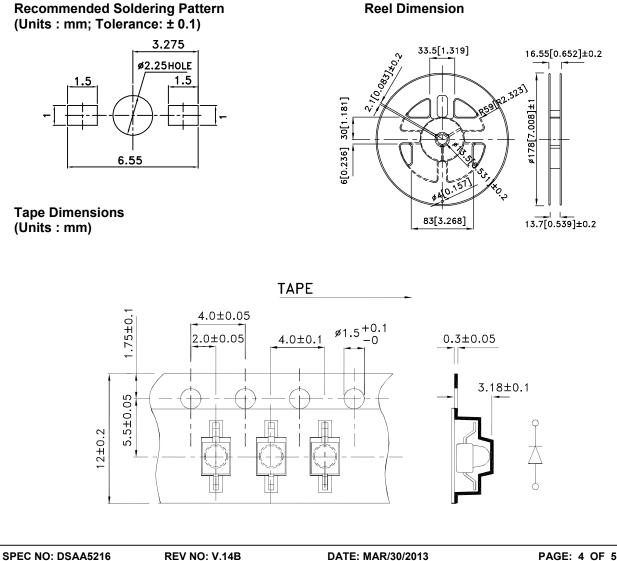
KM2520SGC09

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.



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DRAWN: Y.Liu

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